

Hybrid **MLCAD** 2021 Call for Papers

**3rd ACM/IEEE Workshop on Machine Learning for CAD
August 31 – September 2, 2021**

MLCAD Workshop

This workshop focuses on Machine Learning (ML) methods for all aspects of CAD and electronic system design. The workshop is sponsored by both the ACM Special Interest Group on Design Automation (SIGDA) and the IEEE Council on Electronic Design Automation (CEDA). The workshop program will, in addition to technical presentations, also have keynotes and invited speakers from major CAD and industrial companies who will present their vision on machine learning for CAD.

Paper Submission

Submissions should be full-length papers of up to six pages (PDF format, double-column, US letter size, the IEEE Conference format). Submissions must be anonymous (i.e., double-blind review process). Submissions exceeding 6 pages will be rejected. Submitted papers must describe original work that has not been published/accepted or is currently under review by another journal, conference, or workshop. We encourage senior researchers as well as Ph.D. students to be part of this workshop.

Workshop Proceedings

All accepted papers will be published in a proceedings which will be made available in both IEEE Xplore Digital Library and the ACM Digital Library.

Call for Special Sessions

The MLCAD 2021 organizing committee invites proposals for special sessions. A special session is expected to have a minimum of three, up to six speakers, including the organizers, who provide an overview of the topic area. Prospective organizers of special sessions should submit proposals to the special session chair indicating: title and abstract of the session, organizers, a list of topics (please provide a list of all talks, speakers and their short biographies, co-authors, the contact information of the corresponding author, and an abstract of each contribution).

Venue

MLCAD 2021 will be held in a hybrid format, physically hosted at North Carolina State University, USA and online. Please check the MLCAD website for further details:

<http://mlcad.itec.kit.edu/>

Exemplary topics of interest:

- ML for system-level design
- ML approaches to logic design
- ML for physical design
- ML for analog design
- ML for power and thermal management
- ML for Design Technology Co-Optimization (DTCO)
- ML methods to predict aging and reliability
- Labeled and unlabeled data in ML for CAD
- ML techniques for resource management in many cores
- ML for Verification and Validation

Paper Submission:

May 16, 2021

Author Notification:

July 02, 2021

Camera-ready Version:

July 30, 2021

Early Registration Deadline:

July 30, 2021

Workshop:

August 31 – September 2, 2021

Website:

<http://mlcad.itec.kit.edu/>

General Chairs

Raviv Gal, IBM Research, Haifa

Paul Franzon, North Carolina State University

Program Chairs

Hai (Helen) Li, Duke University

Avi Ziv, IBM Research, Haifa

Special Session Chair

Hussam Amrouch, University of Stuttgart

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